

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-9 (canceled)

10. (original) An integrated circuit package comprising:
a first leadframe;
a second leadframe laminated to a portion of said first leadframe in order to create a multi-layer laminated leadframe; and
a semiconductor die mounted to another portion of said first leadframe.

11. (original) The integrated circuit package according to claim 10, further comprising a plurality of contact balls mounted on said semiconductor die.

12. (original) The integrated circuit package according to claim 10, further comprising:
a third leadframe laminated to at least a portion of said semiconductor die.

13. (original) The integrated circuit package according to claim 10, wherein said first leadframe comprises a copper strip having silver plating on one surface and said second leadframe is soldered to an opposing second surface thereof.

14. (original) The integrated circuit package according to claim 10, wherein said second leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

15. (original) The integrated circuit package according to claim 12, wherein said third leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

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16. (original) The integrated circuit package according to claim 10 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.